2SC3938

Silicon NPN epitaxial planar type

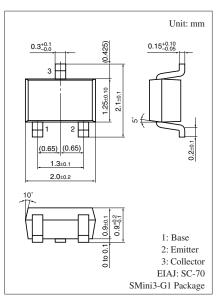
For high-speed switching

Features

- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Matings $T_a = 25$ C					
Parameter	Symbol	Rating	Unit		
Collector-base voltage (Emitter open)	V _{CBO}	40	V		
Collector-emitter voltage (E-B short)	V _{CES}	40	V		
Emitter-base voltage (Collector open)	V _{EBO}	5	V		
Collector current	I _C	100	mA		
Peak collector current	I _{CP}	300	mA		
Collector power dissipation	P _C	150	mW		
Junction temperature	Tj	150	°C		
Storage temperature	T _{stg}	-55 to +150	°C		

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: 2Y

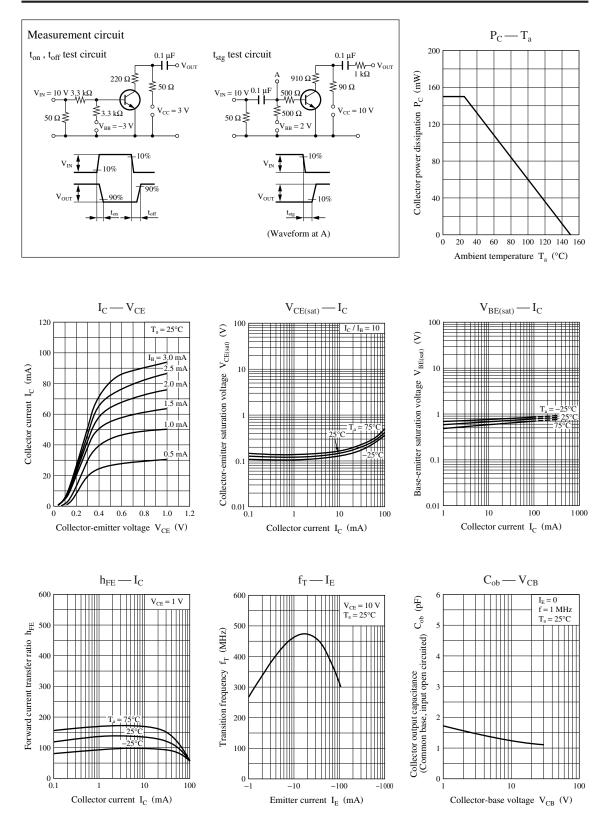
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 40 V, I_E = 0$			0.1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 4 V, I_C = 0$			0.1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 1 \text{ V}, I_{C} = 10 \text{ mA}$	60		200	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{C} = 10 \text{ mA}, I_{B} = 1 \text{ mA}$		0.17	0.25	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{C} = 10 \text{ mA}, I_{B} = 1 \text{ mA}$			1	V
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$		450		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2	6	pF
Turn-on time	t _{on}	Refer to the measurement circuit		17		ns
Turn-off time	t _{off}			17		ns
Storage time	t _{stg}			10		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R
h _{FE}	60 to 120	90 to 200



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